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contacting means for sequentially contacting a distal end of the probe tip and the shank of the spring contact probe,

positioning means for controlling X, Y and Z axis movements of said

contacting means in order to contact the distal end and the shank,

measuring means for measuring the heights of [each contacted point] the distal end and the shank based on a position of the positioning means when contacting the distal end and the shank with the contacting means, and

calculating means for determining a difference in the [two] measured heights of the distal end and the shank, said difference being representative of the length of the probe tip.

Please add new claims 13-18 as follows:

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~~13.~~ (New) An integrated circuit probe card inspection system according to claim 1, wherein the positioning means initially determines a location of an individual probe in the probe array, and thereafter determines an orientation of the probe array and locations of other probes in the probe array based on expected locations of the other probes relative to the location of the individual probe.

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14. (New) An integrated circuit probe card inspection system according to claim ¹³13, wherein the positioning means comprises a probe pin for electrically contacting the individual probe in order to identify the individual probe from among the other probes in the probe array.

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15. (New) An integrated circuit probe card inspection system according to claim ¹³13, wherein the positioning means comprises means for distinguishing bus probes from individual probes among the probes in the probe array.

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16. (New) The apparatus of claim ⁸8, wherein the contacting means comprises a probe pin extending towards the spring contact probe.

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17. (New) The apparatus of claim ¹⁶16, wherein the positioning means comprises a movable stage on which the probe pin is located.